

# MA2SP050G

## Silicon epitaxial planar type

For high frequency attenuator

### ■ Features

- High performance forward current  $I_F$  controlled forward dynamic resistance  $r_f$
- Small terminal capacitance  $C_t$
- Miniature package and surface mounting type

### ■ Package

- Code  
SSMini2-F4
- Pin Name  
1: Anode  
2: Cathode

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

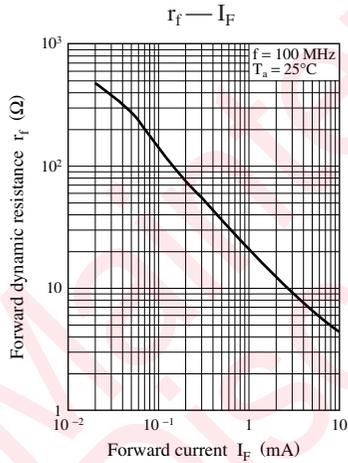
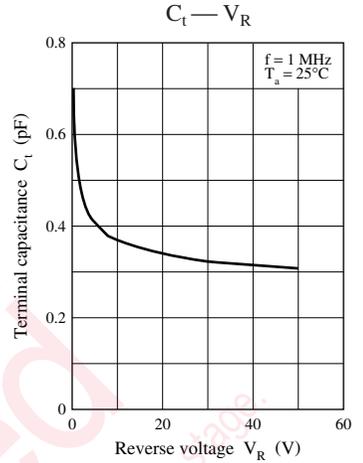
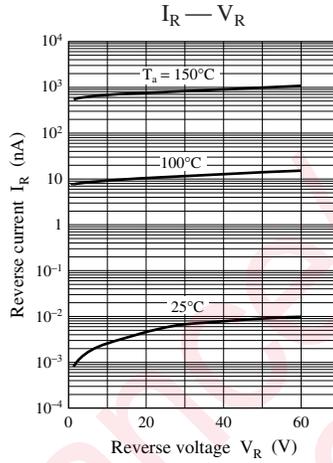
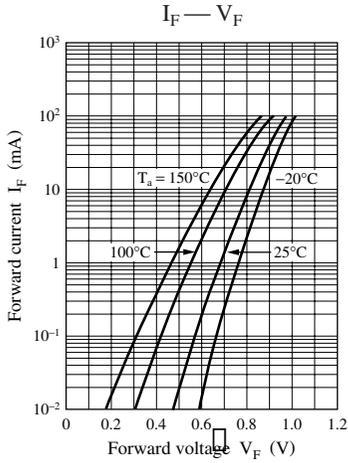
Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	60	V
Forward current	$I_F$	50	mA
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$

### ■ Marking Symbol: 6P

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 10 \text{ mA}$			1.0	V
Reverse current	$I_R$	$V_R = 60 \text{ V}$			100	nA
Terminal capacitance	$C_t$	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			2.4	pF
Forward dynamic resistance	$r_f$	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$			5.5	$\Omega$

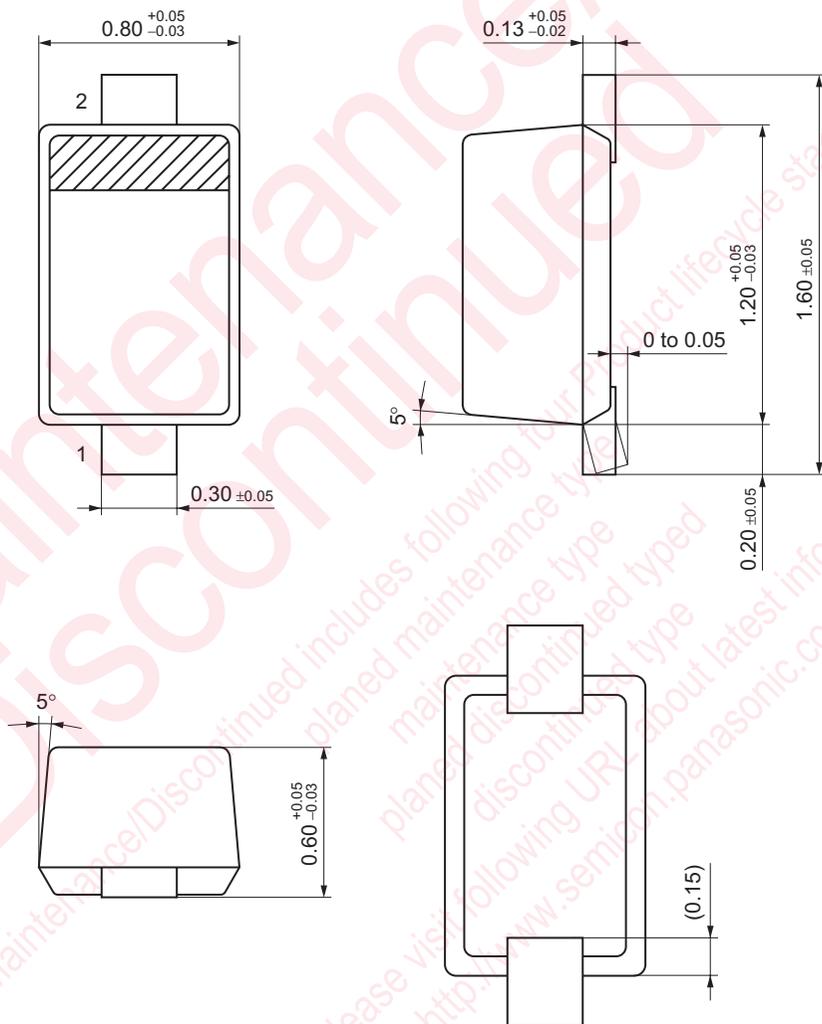
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.



Maintenance/Discontinued includes following four Product lifecycle stage:  
 planned maintenance type  
 maintenance type  
 planned discontinued type  
 discontinued type  
 Please visit following URL about latest information.  
<http://www.semicon.panasonic.co.jp/en/>

SSMini2-F4

Unit: mm



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